



# IEEE MTT-S International Microwave Symposium

*Microwaves on My Mind*



June 15-20, 2008  
Atlanta, Georgia  
[www.ims2008.org](http://www.ims2008.org)



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## Microwave Application Seminars Call for Papers

The Microwave Application Seminars (MicroApps) at the IEEE MTT-S International Microwave Symposium 2008 (IMS 2008) will be held in Atlanta, Georgia, Tuesday, June 17 through Thursday, June 19, 2008. Exhibitors are invited to submit applications engineering technical papers describing state-of-the-art products and processes of interest to the microwave.

**Electronic Paper Submission:** Technical papers for this symposium must be submitted via email to [microapps@jacketmicro.com](mailto:microapps@jacketmicro.com). Do not submit your paper to Horizon House or Microwave Journal.

## Electronic Submission Deadlines

Abstract for Review:

December 7, 2007

Final Manuscripts (CD ROM):

March 7, 2008

All submissions must be made through email:

[microapps@jacketmicro.com](mailto:microapps@jacketmicro.com)

## ALL SUBMISSIONS MUST BE IN PDF FORM

**Hard copies not accepted**

### A Paper Submission consists of:

1. Author information: name(s), title(s), affiliation, telephone number, and email address.
2. A 30-50 word abstract in PDF (Acrobat V6.0 or newer) format. Do not use a zip file. Describe the product or process, its importance to the microwave community, and how it advances the state-of-the-art in an application.
3. A statement using company letterhead authorizing IMS 2008 to print your abstract and publish your technical presentation on CD ROM if your paper is selected.

The decision to accept a paper for presentation at the seminar is based on this summary and confirmation that your affiliation is a registered exhibitor at IMS 2008.

**Paper Selection Criteria:** All submissions (text must be in English) are reviewed by the Microwave Application Seminar Committee. The selection process will consider originality, clarity, and interest to MTT-S membership. Papers can cover new products, especially popular state-of-the-art components, new technologies, and manufacturing and design techniques incorporating the exhibitor's products and technologies. Presentations are typically 20 minutes in length; PowerPoint presentations are preferred. The presentations are adjacent to the exhibit floor and papers should appeal to the exhibit attendees.

Each exhibitor is invited to submit an abstract detailing an applications presentation they would like to present. The committee will try to select every paper that meets the selection criteria.

Allotted presentation time may be reduced for multiple submissions from each exhibitor. The file for the CD shall not exceed 15MB. The CD is offered free of charge to all MicroApps attendees. Presentation should be by digital projection using the session PC.

### Notification:

Authors will be notified of the evaluation result in January 2008.

# Possible Areas of Interest

## **CAD and Modeling Products and Techniques**

- Design for Testability
- Design for Manufacturability
- System Design

## **Mechanical and Passive Components**

- Transmission Lines
- Filters and Multiplexers
- Ferrite and Acoustic Components
- Conventional Passive Devices
- MEMS
- Integrated Passive Devices

## **Active Components**

- Digital and Mixed Signal Circuits
- Oscillators and Frequency Sources
- RF Power Devices and Amplifiers
- Low Noise Receivers and Components
- Monolithic Microwave Integrated Circuits
- New Semiconductor Technologies
- Optoelectronics for Microwave / Millimeter-wave Applications
- Superconducting Components and Technology
- Switches, Phase Shifters, Limiters, Mixers, Frequency Multipliers
- Emerging Technologies (GaN)

## **Sub-Assemblies**

- Hybrids and Modules
- Microwave Systems
- Wireless and Cellular Communications
- Broadband Communication
- Sensors and Sensor Systems
- RFID

## **Instrumentation and Measurement Techniques**

- MMIC Testing
- Assembly Test Techniques
- Basic RF and Microwave Test Procedures
- Wafer and Die RF Probe
- Extreme Environments Evaluation

## **Packaging and Interconnects**

- Multi-Chip Modules
- Substrates
- Flip-Chip

## **Manufacturing Processes**

- Solderability
- Plating
- Coating
- Adhesives
- Sealing and Packaging